

RF SWITCH CG2409M2

High Power SPDT RF Switch

DESCRIPTION

 The CG2409M2 is a GaAs MMIC high power SPDT (Single Pole Double Throw) switch which was designed for WiMAX and Wireless LAN applications

FEATURES

- Control voltage:
 VC(H) = 1.8 to 5.0 V (3.0V TYP.)
 VC(L) = -0.2 to 0.2 V (0V TYP.)
- Low insertion loss:
 L_{ins}1 = 0.35 dB TYP. @ f = 1.0 GHz

 L_{ins} 1 = 0.33 dB TYP. @ f = 1.0 GHz L_{ins} 2 = 0.42 dB TYP. @ f = 2.5 GHz L_{ins} 3 = 0.45 dB TYP. @ f = 3.0 GHz

High isolation:

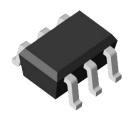
ISL1 = 34 dB TYP. @ f = 1.0 GHz ISL2 = 30 dB TYP. @ f = 2.5 GHz ISL3 = 26 dB TYP. @ f = 3.0 GHz

Power Handling

 $P_{in(0.1dB)} = +36.5 \text{ dBm TYP.}$ @ f = 0.4 to 3.8 GHz, VC(H) = 3.0 V, VC(L) = 0 V

PACKAGE

 6-pin mini mold Package (2.0mm x 1.25mm x 0.9mm)



APPLICATIONS

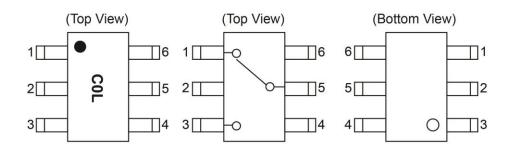
 WiMAX and wireless LAN (IEEE802.11 b/g/n)

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Description
CG2409M2	CG2409M2-C4	6-pin mini mold (Pb-Free)	C0L	 Embossed Tape 8 mm wide Pin 4, 5, 6 face the perforation side of the tape
				MOQ 10 kpcs/reel
CG2409M2-EVAL	CG2409M2-EVAL			 Evaluation Board with DC block capacitors, power supply bypass capacitors, and RF and DC connectors MOQ 1



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	RF1
2	GND
3	RF2
4	VC2
5	RFC
6	VC1

TRUTH TABLE

VC1	VC2	RFC-RF1	RFC-RF2
High	Low	ON	OFF
Low	High	OFF	ON

ABSOLUTE MAXIMUM RATINGS

(TA = +25 °C, unless otherwise specified)

, , , ,			
Parameter	Symbol	Rating	Unit
Control Voltage	VC	6.0 ^{Note 1}	V
Input Power	Pin	+38.0 ^{Note 2}	dBm
Operating Ambient Temperature	T _A	-45~+85	°C
Storage Temperature	T_{stg}	-55~+150	°C

Note 1. |VC1 - VC2|≦6.0V

2. $3.0V \le |VC1 - VC2| \le 5.0V$, $0.4GHz \le f \le 3.8GHz$

RECOMMENDED OPERATING RANGE

(TA = +25 °C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.05	-	3.8	GHz
Switch Control Voltage (H)	VC(H)	+1.8	+3.0	+5.0	V
Switch Control Voltage (L)	VC(L)	-0.2	0	+0.2	V



ELECTRICAL CHARACTERISTICS

(TA=+25 °C, VC(H)=3.0V, VC(L)=0V, Zo=50Ω, DC Block Capacitance=8pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	Lins1	f = 0.05 to 0.5 GHz Note 1	-	0.35	0.55	dB
	Lins2	f = 0.5 to 1.0 GHz Note 2	-	0.35	0.55	dB
	Lins3	f = 1.0 to 2.0 GHz Note 2	-	0.40	0.60	dB
	Lins4	f = 2.0 to 2.5 GHz	-	0.42	0.62	dB
	Lins5	f = 2.5 to 3.0 GHz	-	0.45	0.70	dB
	Lins6	f = 3.0 to 3.8 GHz	-	0.50	0.80	dB
Isolation	ISL1	f = 0.05 to 0.5 GHz Note 1	32	35	-	dB
	ISL2	f = 0.5 to 1.0 GHz Note 2	31	34	-	dB
	ISL3	f = 1.0 to 2.0 GHz Note 2	29	32	-	dB
	ISL4	f = 2.0 to 2.5 GHz	27	30	-	dB
	ISL5	f = 2.5 to 3.0 GHz	23	26	-	dB
	ISL6	f = 3.0 to 3.8 GHz	18	21	-	dB
Return Loss	RL1	f = 0.05 to 0.5 GHz Note 1	15	20	-	dB
	RL2	f = 0.5 to 2.0 GHz Note 2	15	20	-	dB
	RL3	f = 2.0 to 3.8 GHz	15	20	-	dB
0.1 dB Loss Compression Input Power Note 3	P _{in(0.1dB)}	f = 0.4 to 3.8 GHz	-	+36.5	-	dBm
2nd Harmonics	2f0	f = 2.5 GHz, P _{in} =+26dBm	-	80	-	dBc
3rd Harmonics	3f0	f = 2.5 GHz, P _{in} =+26dBm	-	85	-	dBc
Input 3rd Order Intercept Point	IIP3	f = 2.5GHz 2-tone 1MHz Spacing	-	+62	-	dBm
Error Vector Magnitude	EVM	802.11g, 64QAM, 54Mbps, Pin≦+25dBm	-	0.5	-	%
Switch Control Speed	tsw	50% CTL to 90/10% RF	-	100	-	ns
Switch Control Current	Icont	Non RF	-	7	-	μA

Note 1 DC block capacitance = 1,000pF at f=0.05 to 0.5 GHz

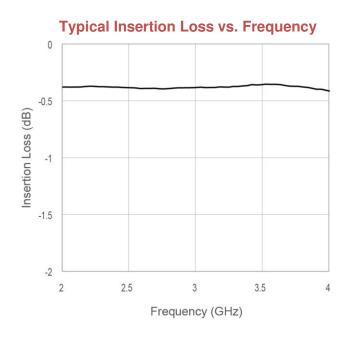
Note 2 DC block capacitance = 56pF at f=0.4 to 2.0 GHz

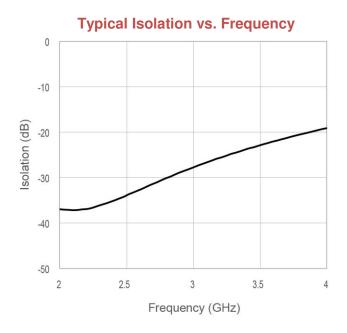
Note 3 $P_{in}(0.1dB)$ is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

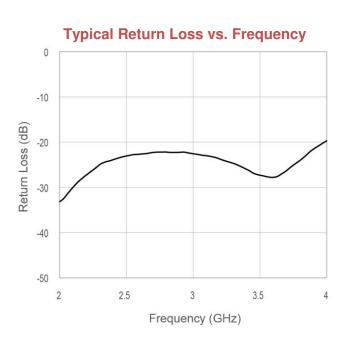


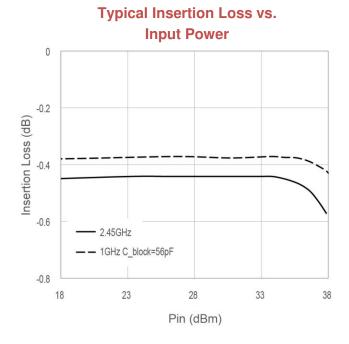
TYPICAL CHARACTERISTICS

 $(VC(H)=3V, VC(L)=0V, T_A=+25^{\circ}C, DC Block Capacitance=8pF, unless otherwise specified. Through board loss is subtracted in insertion loss data)$



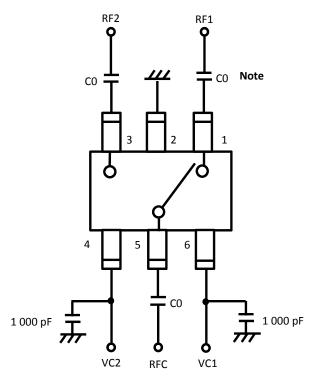








EVALUATION CIRCUIT



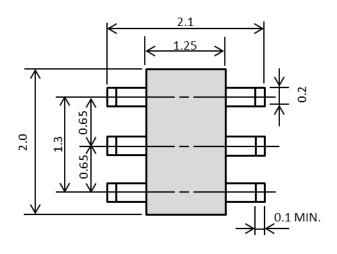
Note C0: 0.05 to 0.5 GHz 1,000pF

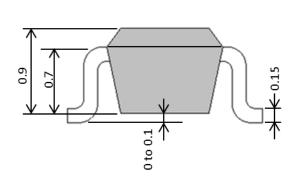
: 0.4 to 2.0 GHz 56pF : 2.0 to 3.8 GHz 8pF

The application circuits and their parameters are for reference only and are not intended for use in actual designs. DC Block Capacitors are required at all RF ports.

PACKAGE DIMENSIONS

6-pin mini mold package (Unit: mm)







RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on CEL's Part Summary page under Associated Documents



REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0032-01 (Issue A)	Preliminary Datasheet	N/A
September 14, 2016		
CDS-0032-02 (Issue B)	Revised Electrical Characteristics table	3, 5
December 27, 2016	Added "Recommended Soldering Conditions" section	
CDS-0032-03 (Issue C)	Initial datasheet	3
March 14, 2017	Revised Electrical Characteristics table	
CDS-0032-04 (Issue D)	Updated Applications section	1, 3, 4
September 14, 2017	Updated Characteristics tables and added Error Vector Magnitude	
	Added "Typical Characteristics" graphs section	



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[CAUTION]

This product uses gallium arsenide (GaAs) of the toxic substance appointed in laws and ordinances. GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not dispose in fire or break up this product.
- Do not chemically make gas or powder with this product.
- When discarding this product, please obey the laws of your country.
- Do not lick the product or in any way allow it to enter the mouth.

[CAUTION]

Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

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